



CERTIFICATE OF MAILING 37 C.F.R. § 1.8

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July 21, 2004 Date

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit: 2811

Examiner: Unknown

Customer No.: 23720

Atty. Dkt. No.: 2000.108400/DE0349

In re Application of:

KARSTEN WIECZOREK ROLF GEILENKEUSER JÖRG-OLIVER WEIDNER

Serial No.: 10/649,051

Filed: August 27, 2003

For: INTEGRATED SEMICONDUCTOR STRUCTURE FOR RELIABILITY TESTS OF DIELECTRICS

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INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

In compliance with the duty of disclosure under 37 C.F.R. § 1.56, it is respectfully requested that this Information Disclosure Statement be entered and the documents listed on attached Form PTO-1449 be considered by the Examiner and made of record. Copies of the listed foreign patent documents and journal articles required by 37 C.F.R. § 1.98(a)(2) are enclosed for the convenience of the Examiner. Because the filing date of the present application is after June 30, 2003, copies of the listed U.S. patents are not included.

In accordance with 37 C.F.R §§ 1.97(g),(h), this Information Disclosure Statement is not

to be construed as a representation that a search has been made, and is not to be construed to be

an admission that the information cited is, or is considered to be, material to patentability as

defined in 37 C.F.R. § 1.56(b).

In accordance with 37 C.F.R § 1.97(e)(1), Applicants hereby certify that each item of

information contained in this Information Disclosure Statement was cited in a communication

from a foreign patent office in a counterpart foreign application not more than three months prior

to the filing of the present statement, as evidenced by the date of the enclosed letter from our

associate in Germany.

Applicants respectfully request that the listed documents be made of record in the present

case.

Respectfully submitted,

WILLIAMS, MORGAN & AMERSON

CUSTOMER NUMBER 23720

Date: July 21, 2004

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Form PTO-1449 (modified)

List of Patents and Publications for App

INFORMATION DISCLOSURE STATEMENT

(Use several sheets if necessary)

Atty. Docket No. Serial No. 2000.108400/DE0349 10/649,051

Applicant

Karsten Wieczorek, Rolf Geilenkeuser and Jörg-Oliver

Weidner

Filing Date: August 27, 2003 Group: 2811

U.S. Patent Documents See Page 1

Foreign Patent Documents See Page 1

Other Art See Page 1

U.S. Patent Documents

Exam. Init.	Ref. Des.	Document Number	Date	Name	Class	Sub Class	Filing Date of App.
	A1	6,472,233 B1	10/29/02	Ahmed et al.	438	14	
	A2	2002/0033710 A1	3/21/02	Kim	324	765	
	A3						
	A4						
	A5						

Foreign Patent Documents

Exam. Init.	Ref. Des.	Document Number	Date	Country	Class	Sub Class	Translation Yes/No
	B1	DE 100 10 285 A1	9/13/01	Germany	H01L	23/544	No
	B2						
	В3						

Other Art (Including Author, Title, Date Pertinent Pages, Etc.)

Exam. Init.	Ref. Des.	Citation				
	C1	Kim et al., "Breakdown Phenomena in MIS Structure," Proc. Of 3 rd Int'l Conf. on Properties and Application of Dielectric Materials, Tokyo, Japan, pp. 164-168, July 8-12, 1991.				
	C2	Shanware <i>et al.</i> , "Reliability evaluation of HiSiON gate dielectric film with 12.8 Å SiO ₂ equivalent thickness," <i>IEEE</i> , pp. 6.6.1-6.6.4, 2001.				
	C3	Abadeer et al., "Key measurements of ultrathin gate dielectric reliability and in-line monitoring," IBM J. Res. Develop., 43:407-16, 1999.				

EXAMINED:	_							
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DATE CONSIDERED:

EXAMINER: INITIAL IF REFERENCE CONSIDERED, WHETHER OR NOT CITATION IS IN CONFORMANCE WITH MPEP609; DRAW LINE THROUGH CITATION IF NOT IN CONFORMANCE AND NOT CONSIDERED. INCLUDE COPY OF THIS FORM WITH NEXT COMMUNICATION TO APPLICANT.